
Some Challenges in the Area of Thermal Issues

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Accuracy

- ◆ Convince ourselves that our models are acceptably accurate:
 - Modeling at what level of detail? (e.g., control logic blocks, clock network)
 - Take into account local, rather than average global quantities? (e.g., voltage, leakage power)
 - How to model power delivery accurately?
 - How can we design and experiment with better sensors (IBM Power 5)?

Why? Because we are less able to use
“intuition sanity check” to validate our conclusions



Scope

- ◆ Understand the division of labor between microarchitecture/compiler/OS
 - Temperature variations are slow (e.g. for a power density of 1 W/mm², T changes 0.1 degrees in about 25-100 usec)*
 - Microarchitecture responds quickly, has low overhead, but adds complication
 - Software is typically the opposite, plus it may have future knowledge

Why? In the T world, things take longer to occur than in the hardware microarchitecture world

* David Skadron, ISCA 2004 tutorial



Different Mindset

- ◆ Often key is **rate of change of events** rather than **absolute number of events**
 - DI/dt
 - Cooling rate also important
 - Jude's point
- ◆ Inderdependences between different problems:
 - Power control schemes introduce I spikes, which affects voltage

Why? We come from simpler, more static environments: increase performance

